

# 2SB1623A

## Silicon PNP epitaxial planar type

For power amplification

### ■ Features

- High forward current transfer ratio  $h_{FE}$
- Satisfactory linearity of forward current transfer ratio  $h_{FE}$
- Dielectric breakdown voltage of the package: > 5 kV

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-80	V
Collector-emitter voltage (Base open)	$V_{CEO}$	-80	V
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V
Collector current	$I_C$	-4	A
Peak collector current	$I_{CP}$	-8	A
Collector power dissipation	$P_C$	40	W
		2.0	
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

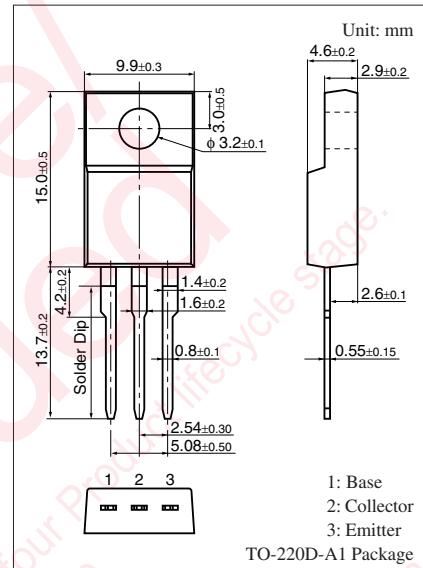
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

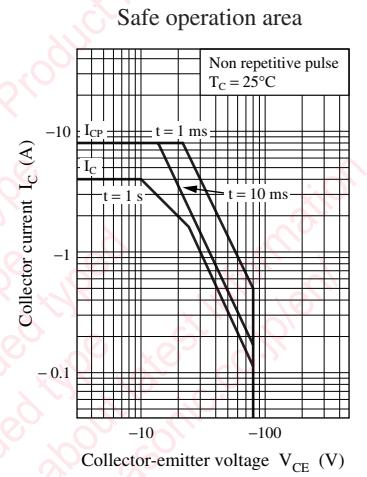
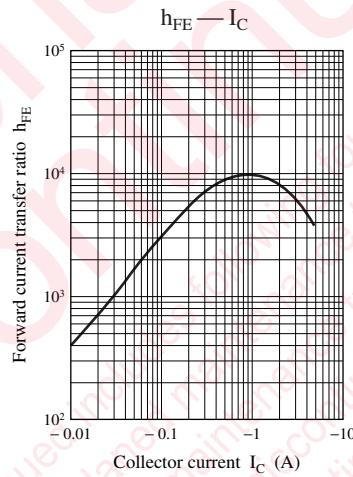
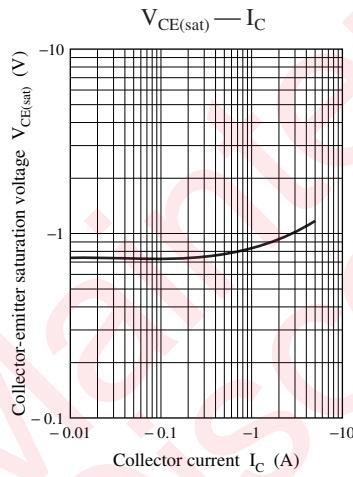
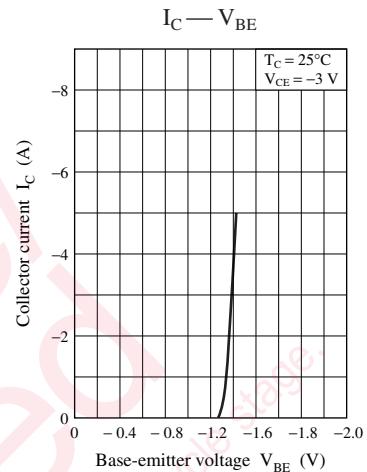
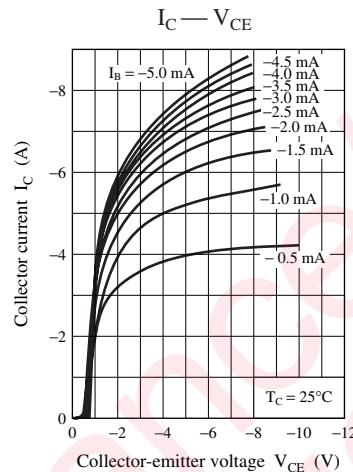
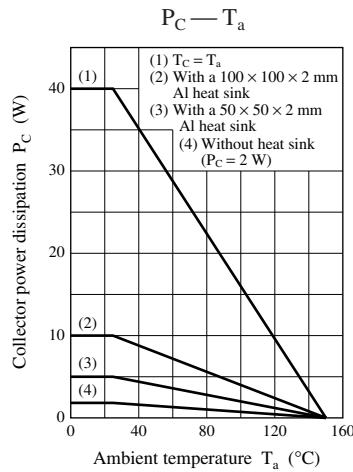
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -30 \text{ mA}, I_B = 0$	-80			V
Base-emitter voltage	$V_{BE}$	$V_{CE} = -3 \text{ V}, I_C = -3 \text{ A}$			-2.5	V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -80 \text{ V}, I_E = 0$			-200	$\mu\text{A}$
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -40 \text{ V}, I_B = 0$			-500	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -5 \text{ V}, I_C = 0$			-2	mA
Forward current transfer ratio	$h_{FE1}$	$V_{CE} = -3 \text{ V}, I_C = -0.5 \text{ A}$	1000			—
	$h_{FE2}^*$	$V_{CE} = -3 \text{ V}, I_C = -3 \text{ A}$	1000		10000	
Collector-emitter saturation voltage	$V_{CE(sat)1}$	$I_C = -3 \text{ A}, I_B = -12 \text{ mA}$			-2	V
	$V_{CE(sat)2}$	$I_C = -5 \text{ A}, I_B = -20 \text{ mA}$			-4	
Transition frequency	$f_T$	$V_{CE} = -10 \text{ V}, I_C = -0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time	$t_{on}$	$I_C = -3 \text{ A}, I_{B1} = -12 \text{ mA}, I_{B2} = 12 \text{ mA}$		0.3		$\mu\text{s}$
Storage time	$t_{stg}$	$V_{CC} = -50 \text{ V}$		2.0		$\mu\text{s}$
Fall time	$t_f$			0.5		$\mu\text{s}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*: Rank classification

Rank	R	Q	P
$h_{FE2}$	1000 to 2500	2000 to 5000	4000 to 10000





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